MSKSEMI 美森科













ESD

TVS

TSS

MOV

GDT

PLED

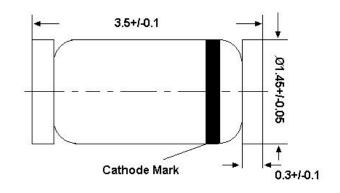
LLDB3/LLDB4

Product specification





These diacs are intended for use in thyristor phase control, circuits for lamp-dimming, universal-motor speed controls, and heat controls.



Glass case MiniMELF Dimensions in mm

LL-34

REEL SPECIFICATION

P/N	PKG	QTY
LLDB3/LLDB4	LL-34	2500

Absolute Maximum Ratings (Ta = 25℃)

Parameter	Symbol	Value	Unit	
Power Dissipation ($T_a = 65 ^{\circ}C$)	P _{tot}	150	mW	
Repetitive Peak On-state Current (tp = 20 µs, f = 100 Hz)	I _{TRM}	2	А	
Operating Junction and Storage Temperature Range	T _j , T _{stg}	- 40 to + 125	°C	

Characteristics at Ta = 25° C)

Parameter		Symbol	Min.	Max.	Unit
Breakover Voltage	LLDB3	V _{BO}	28	36	V
at C = 22 nF, see diagram 1	LLDB4		35	45	
Breakover Voltage Symmetry at C = 22 nF, see diagram 1		[+V _{BO} - -V _{BO}]	-	3	V
Dynamic Breakover Voltage at ΔI = [I _{BO} to I _F = 10 mA]		ΔV ±	5	-	V
Output Voltage See diagram 2		Vo	5	-	V
Breakover Current at C = 22 nF		I _{BO}	-	50	μA
Leakage Current at $V_B = 0.5 V_{BO}$ max		Ι _Β	-	10	μA
Rise Time See diagram 3		tr	-	2	μs



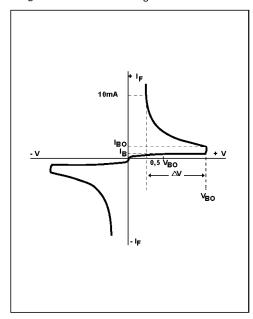


Diagram 1: Current-voltage characteristics

Diagram 2: Test circuit for output voltage

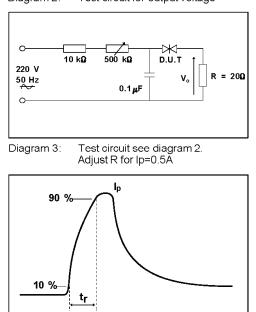


Fig. 1: Power dissipation versus ambient temperature (maximum values)

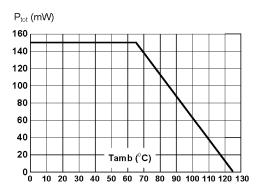


Fig. 3: Peak pulse current versus pulse duration (maximum values)

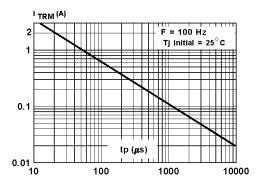
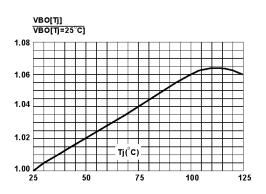


Fig. 2: Relative variation of V_{BO} versus junction temperature (typical values)





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